Annex 1 to ISPM 15:2009 Approved treatments associated with wood packaging material

IPPC Member Consultation

20 June to 30 September

2011

Background

- Call for Topics:
- Added to the *List of Topics for IPPC Standards*: [CPM 1, 2006]
- Specification [31]: [November 2004 approved]
- Drafted by [TPFQ]: [September 2010]
- SC reviewed: [April 2011]
- SC approved for Member Consultation: May 2011

General Considerations

- World-wide experiences in auditing heat treatment chambers showed that more harmonization and explanation is necessary. Therefore, paragraph 17 lists criteria for "good HT practice"
- Dielectric heating as 2nd heating source was proposed to be included in ISPM 15:2009 and ISPM 28:2007

General Considerations

- To be consistent with HT and MB, guidance for the use of dielectric heating (DH) was added
- MB treatment schedule was slightly adjusted to reflect practical application and to meet concerns about the use of MB. In the event of not meeting the required CT, a slight increase of treatment time could avoid a completely new treatment

Drafting Issues

- The TPFQ realized that the types of HT-facilities world-wide differ significantly. The current listing gives advice on the minimum factors to be addressed during approving and auditing heat treatment providers
- It was believed that failure of HT treatments and therefore non-compliance with ISPM 15:2009 was based on incorrect application of the heat or control devices, such as temperature sensors

Drafting Issues

- Aim of all three lists is to give both the treatment provider, as well as the auditor, better confidence that the treatment was applied efficiently

Other relevant information

- The revision of the ISPM 15 explanatory document, prepared by Shane Sela (Canada) is under development. A more detailed section on how to carry out heat treatment using conventional steam or dry heat chambers will either be included in the explanatory document or prepared as a stand alone document